Data sheet acquired from Cypress Semiconductor Corporation.
Data sheet modified to remove devices not offered.

CY74FCT821T
CY74FCT823T
CY74FCT825T

TEXAS INSTRUMENTS

SCCS033 - May 1994 - Revised March 2000

8-/9-/10-Bit Bus Interface Registers

Features

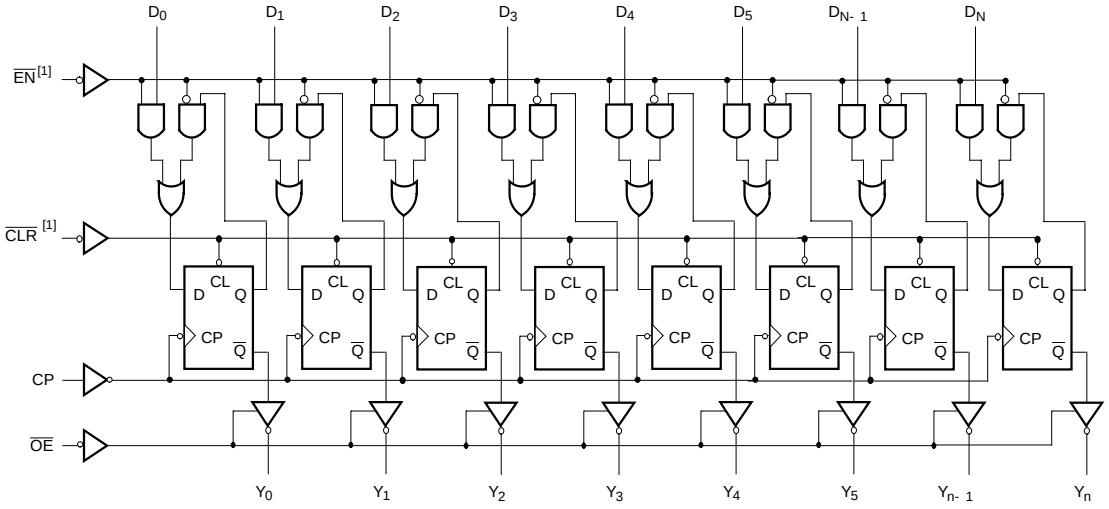
- **Function, pinout, and drive compatible with FCT, F, and Am29821/23/25 logic**
- **FCT-C speed at 6.0 ns max.**
  FCT-B speed at 7.5 ns max.
- **Reduced V_{OH} (typically = 3.3V) versions of equivalent FCT functions**
- **Edge-rate control circuitry for significantly improved noise characteristics**
- **Power-off disable feature**
- **Matched rise and fall times**
- **Fully compatible with TTL input and output logic levels**
- **ESD > 2000V**
- **Sink current 64 mA**
  Source current 32 mA
- **High-speed parallel registers with positive edge-triggered D-type flip-flops**
- **Buffered common clock enable (EN) and asynchronous clear input (CLR)**
- **Extended commercial range of –40˚C to +85˚C**

Functional Description

These bus interface registers are designed to eliminate the extra packages required to buffer existing registers and provide extra data width for wider address/data paths or buses carrying parity. The FCT821T is a buffered, 10-bit wide version of the popular FCT374 function. The FCT823T is a 9-bit wide buffered register with clock enable ($\overline{EN}$) and clear ($\overline{CLR}$) ideal for parity bus interfacing in high-performance microprogrammed systems. The FCT825T is an 8-bit buffered register with all the FCT823T controls plus multiple enables ($\overline{OE}_1$, $\overline{OE}_2$, $\overline{OE}_3$) to allow multiuser control of the interface, e.g., $\overline{CS}$, DMA, and RD/$\overline{WR}$. They are ideal for use as an output port requiring high I_{OL}/I_{OH}.

These devices are designed for high-capacitance load drive capability, while providing low-capacitance bus loading at both inputs and outputs. Outputs are designed for low-capacitance bus loading in the high-impedance state and are designed with a power-off disable feature to allow for live insertion of boards.

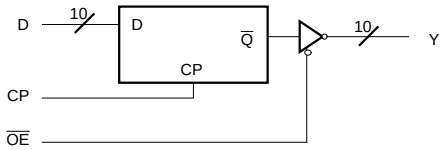
Logic Block Diagram



Note:
1. Not on FCT821.

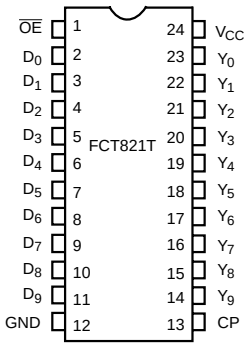
Logic Diagrams

FCT821T (10-Bit Register)

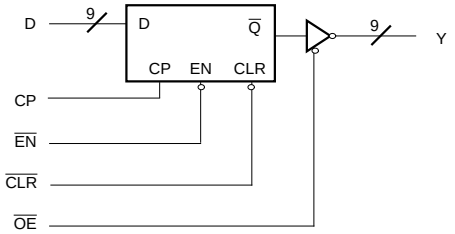


Pin Configurations

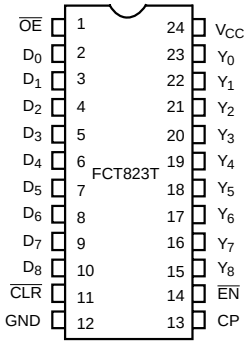
DIP/QSOP/SOIC
Top View



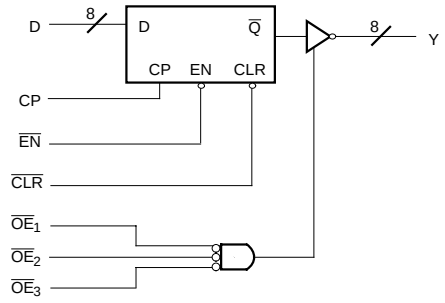
FCT823T (9-Bit Register)



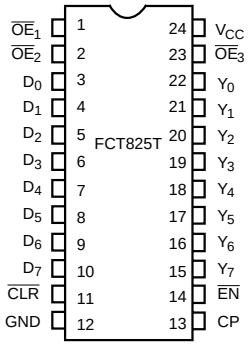
DIP/QSOP/SOIC
Top View



FCT825T (8-Bit Register)



DIP/QSOP/SOIC
Top View



Pin Description

Name	I/O	Description
D	I	The D flip-flop data inputs.
$\overline{CLR}$	I	When $\overline{CLR}$ is LOW and $\overline{OE}$ is LOW, the Q outputs are LOW. When $\overline{CLR}$ is HIGH, data can be entered into the register.
CP	O	Clock Pulse for the register; enters data into the register on the LOW-to-HIGH transition.
Y	O	The register three-state outputs.
$\overline{EN}$	I	Clock Enable. When $\overline{EN}$ is LOW, data on the D input is transferred to the Q output on the LOW-to-HIGH clock transition. When $\overline{EN}$ is HIGH, the Q outputs do not change state, regardless of the data or clock input transitions.
$\overline{OE}$	I	Output Control. When $\overline{OE}$ is HIGH, the Y outputs are in the high-impedance state. When $\overline{OE}$ is LOW, the TRUE register data is present at the Y outputs.

Function Table[2]

Inputs					Internal Outputs		Function
$\overline{OE}$	$\overline{CLR}$	$\overline{EN}$	D	CP	Q	Y	
H H	H H	L L	L H	⌜ ⌜	L H	Z Z	High Z
H L	L L	X X	X X	X X	L L	Z L	Clear
H L	H H	H H	X X	X X	NC NC	Z NC	Hold
H H L L	H H H H	L L L L	L H L H	⌜ ⌜ ⌜ ⌜	L H L H	Z Z L H	Load

Maximum Ratings[3,4]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... −65°C to +150°C

Ambient Temperature with Power Applied ..... −65°C to +135°C

Supply Voltage to Ground Potential ..... −0.5V to +7.0V

DC Input Voltage ..... −0.5V to +7.0V

DC Output Voltage..... −0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin) ..... 120 mA

Power Dissipation 0.5W

Static Discharge Voltage..... >2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Range	Ambient Temperature	V_{CC}
Commercial	All	–40°C to +85°C	5V ± 5%

Notes:

2. H = HIGH Voltage Level, L = LOW Voltage Level, X = Don't Care, NC = No Change, ⌜ = LOW-to-HIGH Transition, Z = HIGH Impedance.
3. Unless otherwise noted, these limits are over the operating free-air temperature range.
4. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Typ.[5]	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –32 mA	2.0			V
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –15 mA	2.4	3.3		V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 64 mA		0.3	0.55	V
V_{IH}	Input HIGH Voltage		2.0			V
V_{IL}	Input LOW Voltage				0.8	V
V_H	Hysteresis[6]	All inputs		0.2		V
V_{IK}	Input Clamp Diode Voltage	V_{CC} = Min., I_{IN} = –18 mA		–0.7	–1.2	V
I_I	Input HIGH Current	V_{CC} = Max., V_{IN} = V_{CC}			5	µA
I_{IH}	Input HIGH Current	V_{CC} = Max., V_{IN} = 2.7V			±1	µA
I_{IL}	Input LOW Current	V_{CC} = Max., V_{IN} = 0.5V			±1	µA
I_{OZH}	Off State HIGH-Level Output Current	V_{CC} = Max., V_{OUT} = 2.7V			10	µA
I_{OZL}	Off State LOW-Level Output Current	V_{CC} = Max., V_{OUT} = 0.5V			–10	µA
I_{OS}	Output Short Circuit Current[7]	V_{CC} = Max., V_{OUT} = 0.0V	–60	–120	–225	mA
I_{OFF}	Power-Off Disable	V_{CC} = 0V, V_{OUT} = 4.5V			±1	µA

Capacitance[6]

Parameter	Description	Typ.[5]	Max.	Unit
C_{IN}	Input Capacitance	5	10	pF
C_{OUT}	Output Capacitance	9	12	pF

Notes:

5. Typical values are at V_{CC}=5.0V, T_A=+25˚C ambient.
6. This parameter is specified but not tested.
7. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ.[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC}=Max., $V_{IN}\leq$0.2V, $V_{IN}\geq V_{CC}$–0.2V	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs HIGH)	V_{CC}=Max., V_{IN}=3.4V,[8] f_1=0, Outputs Open	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current[9]	V_{CC}=Max., One Bit Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}$=$\overline{EN}$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	0.06	0.12	mA/MHz
I_C	Total Power Supply Current[10]	V_{CC}=Max., f_0=10 MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=5 MHz, $\overline{OE}$=$\overline{EN}$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	0.7	1.4	mA
		V_{CC}=Max., f_0=10 MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=5 MHz, $\overline{OE}$=$\overline{EN}$=GND, V_{IN}=3.4V or V_{IN}=GND	1.2	3.4	mA
		V_{CC}=Max., f_0=10 MHz, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, $\overline{OE}$=$\overline{EN}$=GND, $V_{IN}\leq$0.2V or $V_{IN}\geq V_{CC}$–0.2V	1.6	3.2[11]	mA
		V_{CC}=Max., f_0=10 MHz,50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, $\overline{OE}$=$\overline{EN}$=GND, V_{IN}=3.4V or V_{IN}=GND	3.9	12.2[11]	mA

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC}+\Delta I_{CC}D_HN_T+I_{CCD}(f_0/2 + f_1N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are specified but not tested.

Switching Characteristics Over the Operating Range[12]

Param.	Description	Test Load	CY74FCT821AT CY74FCT823AT CY74FCT825AT Commercial Min.	CY74FCT821AT CY74FCT823AT CY74FCT825AT Commercial Max.	CY74FCT821BT CY74FCT823BT CY74FCT825BT Commercial Min.	CY74FCT821BT CY74FCT823BT CY74FCT825BT Commercial Max.	CY74FCT821CT CY74FCT823CT CY74FCT825CT Commercial Min.	CY74FCT821CT CY74FCT823CT CY74FCT825CT Commercial Max.	Unit	Fig. No.[13]
t_{PLH} t_{PHL}	Propagation Delay CP to Y, ($\overline{OE}$=LOW)	C_L=50 pF R_L=500Ω		10.0		7.5		6.0	ns	1, 5
t_{PLH} t_{PHL}	Propagation Delay CP to Y, ($\overline{OE}$=LOW)[6]	C_L=300 pF R_L=500Ω		20.0		15.0		12.5	ns	1, 5
t_{PLH}	Propagation Delay $\overline{CLR}$ to Y	C_L=50 pF R_L=500Ω		14.0		9.0		8.0	ns	1, 5
t_{PZH} t_{PZL}	Output Enable Time $\overline{OE}$ to Y	C_L=50 pF R_L=500Ω		12.0		8.0		7.0	ns	1, 7, 8
t_{PZH} t_{PZL}	Output Enable Time $\overline{OE}$ to Y[6]	C_L=300 pF R_L=500Ω		23.0		15.0		12.5	ns	1, 7, 8
t_{PHZ} t_{PHL}	Output Disable Time $\overline{OE}$ to Y[6]	C_L=5 pF R_L=500Ω		7.0		6.5		6.0	ns	1, 7, 8
t_{PHZ} t_{PHL}	Output Disable Time $\overline{OE}$ to Y	C_L=50 pF R_L=500Ω		8.0		7.5		6.5	ns	1, 7, 8
t_{SU}	Data to CP, Set-Up Time	C_L=50 pF R_L=500Ω	4.0		3.0		3.0		ns	4
t_H	Data to CP, Hold Time		2.0		1.5		1.5		ns	4
t_{SU}	Enable $\overline{EN}$ to CP, Set-Up Time		4.0		3.0		3.0		ns	4
t_H	Enable $\overline{EN}$ to CP, Hold Time		2.0		0.0		0.0		ns	4
t_{REM}	Clear Recovery Time, $\overline{CLR}$ to CP		6.0		6.0		6.0		ns	6
t_W	Clock Pulse Width		7.0		6.0		6.0		ns	5
t_W	$\overline{CLR}$ Pulse Width LOW		6.0		6.0		6.0		ns	5

Notes:

12. Minimum limits are specified but not tested on Propagation Delays.
13. See “Parameter Measurement Information.”

Ordering Information—FCT821T

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
6.0	CY74FCT821CTQCT	Q13	24-Lead (150-Mil) QSOP	Commercial
	CY74FCT821CTSOC/SOCT	S13	24-Lead (300-Mil) Molded SOIC	
7.5	CY74FCT821BTPC	P13/13A	24-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT821BTSOC/SOCT	S13	24-Lead (300-Mil) Molded SOIC	
10.0	CY74FCT821ATQCT	Q13	24-Lead (150-Mil) QSOP	Commercial
	CY74FCT821ATSOC/SOCT	S13	24-Lead (300-Mil) Molded SOIC	

Ordering Information—FCT823T

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
6.0	CY74FCT823CTQCT	Q13	24-Lead (150-Mil) QSOP	Commercial
	CY74FCT823CTSOC/SOCT	S13	24-Lead (300-Mil) Molded SOIC	
7.5	CY74FCT823BTPC	P13/13A	24-Lead (300-Mil) Molded DIP	Commercial
10.0	CY74FCT823ATPC	P13/13A	24-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT823ATQCT	Q13	24-Lead (150-Mil) QSOP	
	CY74FCT823ATSOC/SOCT	S13	24-Lead (300-Mil) Molded SOIC	

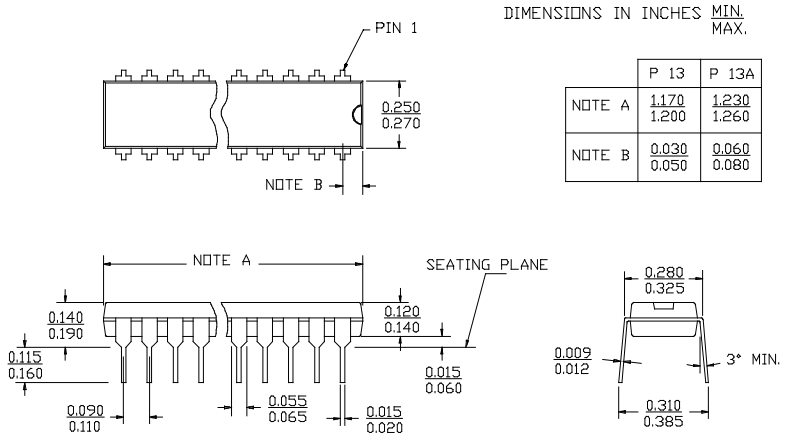
Ordering Information—FCT825T

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
6.0	CY74FCT825CTQCT	Q13	24-Lead (150-Mil) QSOP	Commercial

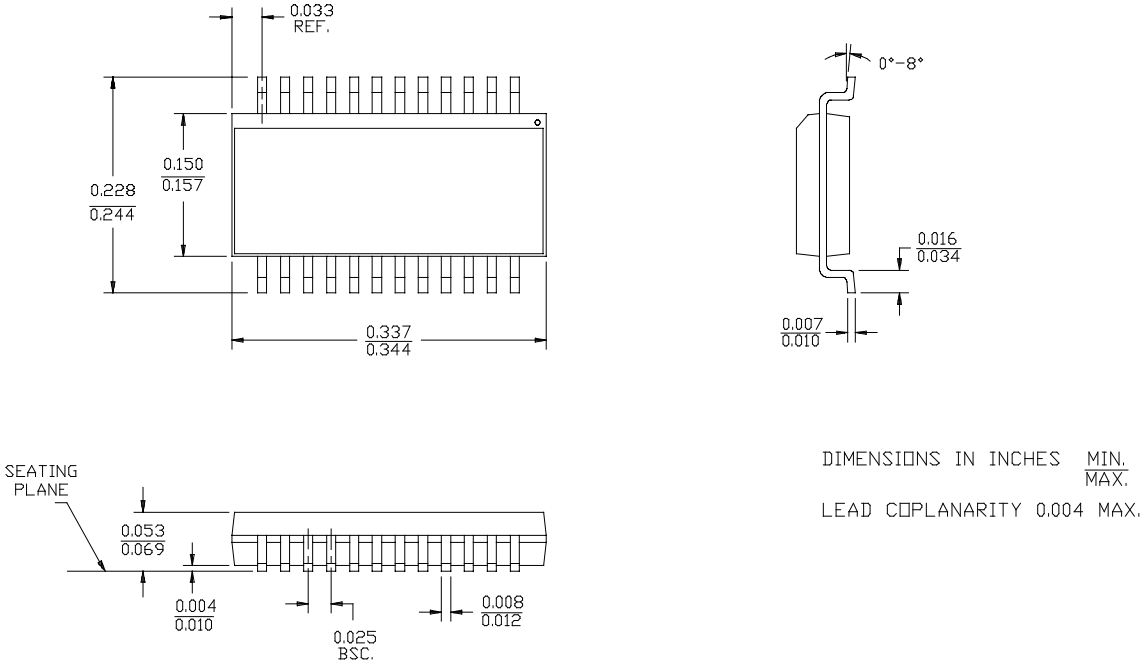
Document #: 38–00282–B

Package Diagrams

24-Lead (300-Mil) Molded DIP P13/P13A

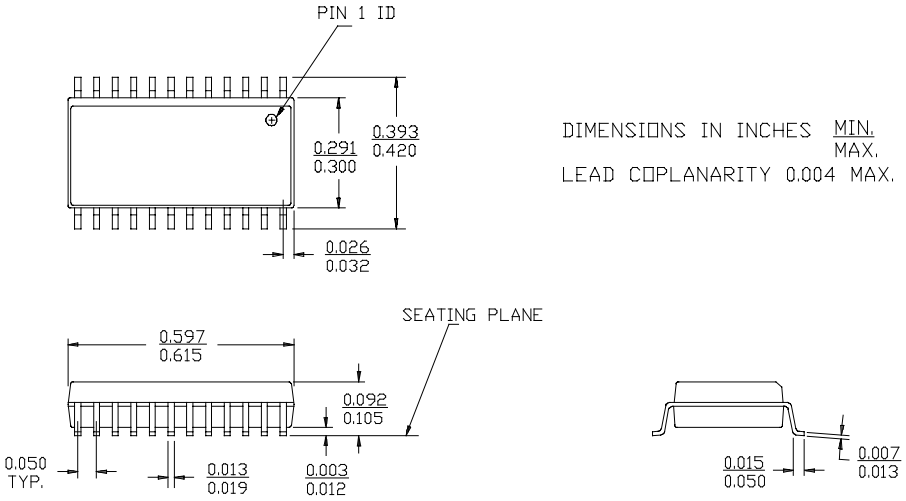


24-Lead Quarter Size Outline Q13



Package Diagrams (continued)

24-Lead (300-Mil) Molded SOIC S13



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